

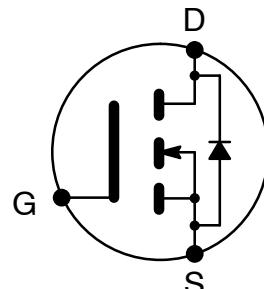


ELECTRONICS, INC.
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NTE2980
Logic Level MOSFET
N-Channel, Enhancement Mode
High Speed Switch
TO251 Type Package

Features:

- Dynamic dv/dt Rating
- Logic Level Gate Drive
- $R_{DS(on)}$ Specified at $V_{GS} = 4V$ & $5V$
- Fast Switching
- TO251 Type Package



Absolute Maximum Ratings:

Drain Current, I_D	
Continuous ($V_{GS} = 5V$)	7.7A
$T_C = +25^\circ C$	4.9A
$T_C = +100^\circ C$	
Pulsed (Note 1)	31A
Total Power Dissipation ($T_C = +25^\circ C$), P_D	25W
Derate Above $25^\circ C$	0.20W/ $^\circ C$
Total Power Dissipation (PC Board Mount, $T_C = +25^\circ C$, Note 2), P_D	2.5W
Derate Above $25^\circ C$	0.02W/ $^\circ C$
Gate-Source Voltage, V_{GS}	$\pm 10V$
Single Pulsed Avalanche Energy (Note 3), E_{AS}	47mJ
Peak Diode Recovery dv/dt (Note 4), dv/dt	4.5V/ns
Operating Junction Temperature Range, T_J	-55° to +150°C
Storage Temperature Range, T_{stg}	-55° to +150°C
Maximum Lead Temperature (During Soldering, 1.6mm from case, 10sec), T_L	+260°C
Maximum Thermal Resistance:	
Junction-to-Case, R_{thJC}	5.0°C/W
Junction-to-Ambient (PCB Mount, Note 2), R_{thJA}	50°C/W
Junction-to-Ambient, R_{thJA}	110°C/W

Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 2. When mounted on a 1" square PCB (FR-4 or G-10 material).

Note 3. $L = 924^\circ H$, $V_{DD} = 25V$, $R_G = 25\Omega$, Starting $T_J = +25^\circ C$, $I_{AS} = 7.7A$.

Note 4. $I_{SD} \leq 10A$, $di/dt \leq 90A/\mu s$, $V_{DD} \leq V_{(BR)DSS}$, $T_J \leq +150^\circ C$.

Electrical Characteristics: ($T_J = +25^\circ\text{C}$ unless otherwise specified)

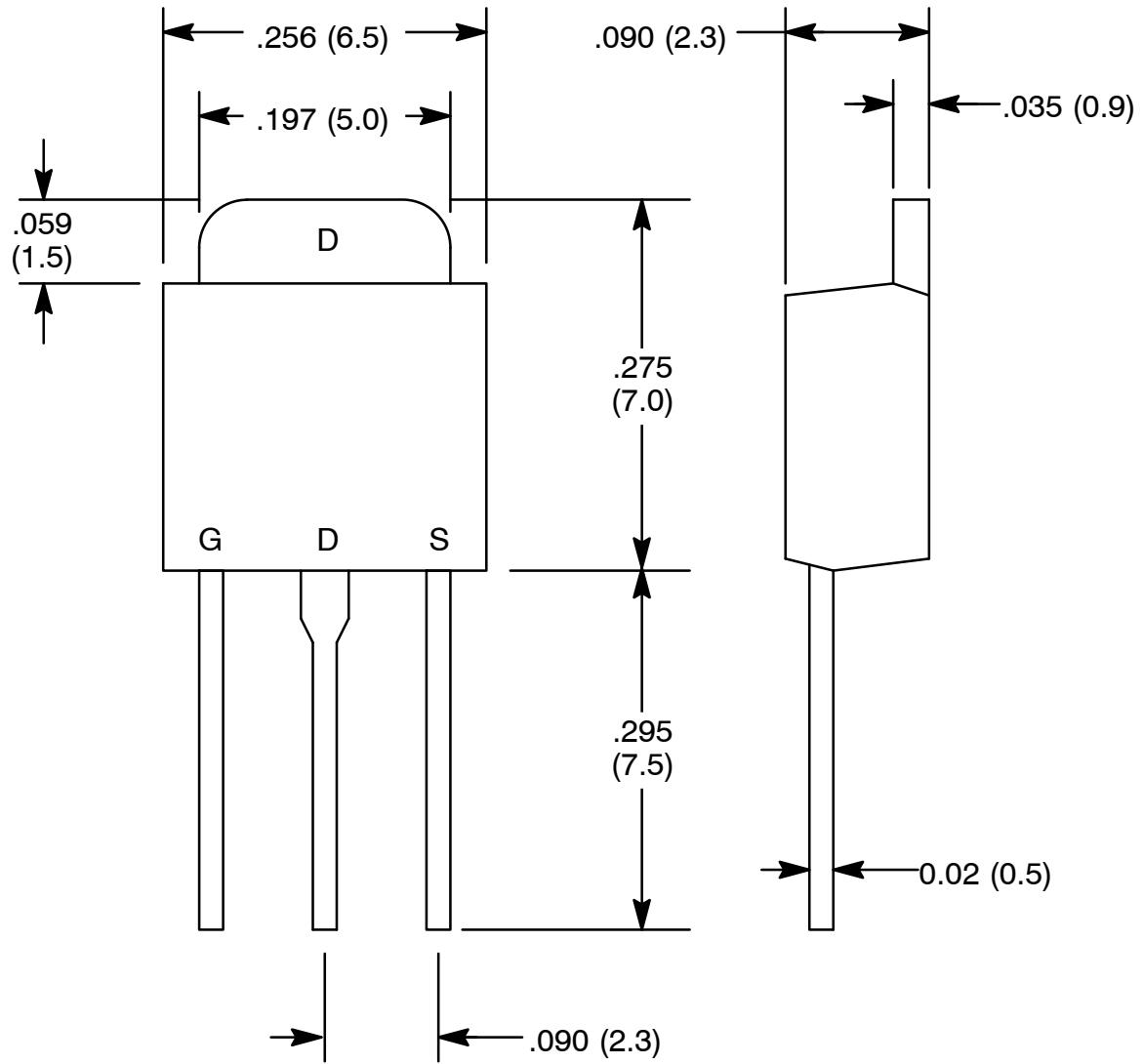
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain–Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250^\circ\text{A}$	60	—	—	V
Breakdown Voltage Temperature Coefficient	$\pm V_{(\text{BR})\text{DSS}}/\pm T_J$	Reference to $+25^\circ\text{C}$, $I_D = 1\text{mA}$	—	0.073	—	$\text{V}/^\circ\text{C}$
Static Drain–Source ON Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 5\text{V}, I_D = 4.6\text{A}$, Note 5	—	—	0.20	\leq
		$V_{\text{GS}} = 4\text{V}, I_D = 3.9\text{A}$, Note 4	—	—	0.28	\leq
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250^\circ\text{A}$	1.0	—	2.0	V
Forward Transconductance	g_{fs}	$V_{\text{DS}} = 25\text{V}, I_D = 4.6\text{A}$, Note 5	3.4	—	—	mhos
Drain-to-Source Leakage Current	I_{DSS}	$V_{\text{DS}} = 60\text{V}, V_{\text{GS}} = 0$	—	—	25	$^\circ\text{A}$
		$V_{\text{DS}} = 48\text{V}, V_{\text{GS}} = 0\text{V}, T_C = +125^\circ\text{C}$	—	—	250	$^\circ\text{A}$
Gate–Source Leakage Forward	I_{GSS}	$V_{\text{GS}} = 10\text{V}$	—	—	100	nA
Gate–Source Leakage Reverse	I_{GSS}	$V_{\text{GS}} = -10\text{V}$	—	—	-100	nA
Total Gate Charge	Q_g	$V_{\text{GS}} = 5\text{V}, I_D = 10\text{A}, V_{\text{DS}} = 48\text{V}$, Note 5	—	—	8.4	nC
Gate–Source Charge	Q_{gs}		—	—	3.5	nC
Gate–Drain (“Miller”) Charge	Q_{gd}		—	—	6.0	nC
Turn–On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 30\text{V}, I_D = 10\text{A}, R_G = 12\leq, R_D = 2.8\leq$, Note 5	—	9.3	—	ns
Rise Time	t_r		—	110	—	ns
Turn–Off Delay Time	$t_{\text{d}(\text{off})}$		—	17	—	ns
Fall Time	t_f		—	26	—	ns
Internal Drain Inductance	L_D	Between lead, 6mm (0.25") from package and center of die contact	—	4.5	—	nH
Internal Source Inductance	L_S		—	7.5	—	nH
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1\text{MHz}$	—	400	—	pF
Output Capacitance	C_{oss}		—	170	—	pF
Reverse Transfer Capacitance	C_{rss}		—	42	—	pF

Source–Drain Diode Ratings and Characteristics

Continuous Source Current	I_S	(Body Diode)	—	—	7.7	A
Pulse Source Current	I_{SM}	(Body Diode) Note 1	—	—	31	A
Diode Forward Voltage	V_{SD}	$T_J = +25^\circ\text{C}, I_S = 7.7\text{A}, V_{\text{GS}} = 0\text{V}$, Note 5	—	—	1.6	V
Reverse Recovery Time	t_{rr}	$T_J = +25^\circ\text{C}, I_F = 10\text{A}, \text{di/dt} = 100\text{A}/^\circ\text{s}$, Note 5	—	65	130	ns
Reverse Recovery Charge	Q_{rr}		—	0.33	0.65	$^\circ\text{C}$
Forward Turn–On Time	t_{on}	Intrinsic turn–on time is neglegible (turn–on is dominated by $L_S + L_D$)				

Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 5. Pulse Test: Pulse Width $\leq 300^\circ\text{s}$, Duty Cycle $\leq 2\%$.



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